



New Trends in Telecommunications Engineering

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Message from the Guest Editor

Telecommunication engineering is continuously helping society, allowing connections between people, things, and people and things. In the recent COVID-19 pandemic, telecommunication is playing a vital role, from wireless sensors that help to monitor ill people to high-speed wireless connections allowing professionals to work, teach, and do webinars from home with colleagues all around the world.

The scope of this Special Issue is to address the latest advances in research and industry applications and milestones on telecommunication engineering, paying attention to one of the most relevant key players: the antenna. Papers dealing with antenna design on real wireless devices are encouraged—for example, those for IoT applications. Other topics within the scope of the current issue are:

- Antennas for IoT;
- Antennas for medical applications;
- Antennas for wearable devices;
- Antennas for mobile communications;
- Manufacturing methods for antennas;
- Materials for antenna design: transparent conductors, metamaterials, metalized foams, graphene, etc.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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